

### Features

- Small size (3.2x1.5mm)
- SMD

### Applications

- Small mobile devices
- Clock
- Wireless LAN

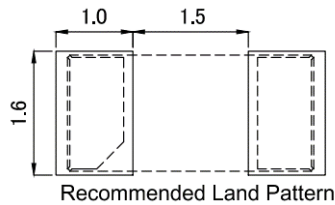
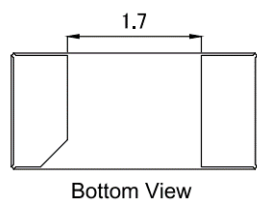
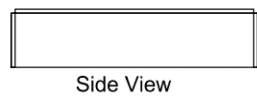
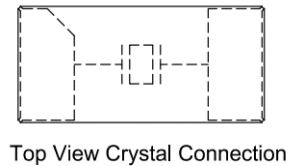
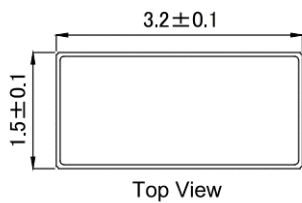


### BC3215A Series

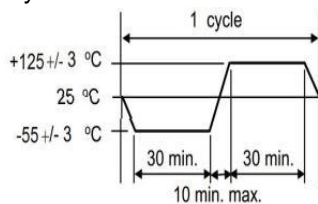
Parameters	Value			Units	Conditions
	MIN	TYP	MAX		
Nominal Frequency(F0)	32.768			KHz	
Mode of Oscillation	Foundation				AT-CUT
Frequency Tolerance(FL)	±10	–	±50	ppm	+25°C ± 2°C
Frequency Stability over Temperature(TL)	±10	–	±50	ppm	-40°C ~ +85°C
Load Capacitance(CL)	12.5			pf	
Drive Level(DL)	±1	–	±200	uW	
Equivalent Series Resistance (RR)	–	–	70	Ω	
Shunt Capacitance (C0)	–	–	3	pf	
Insulation Resistance (IR)	500	–		MΩ	DC 100V
Aging	±2			ppm	
Operating Temperature Range	-40	–	85	°C	
Storage Temperature Range	-55	–	125	°C	

### Dimension

Dimension: mm

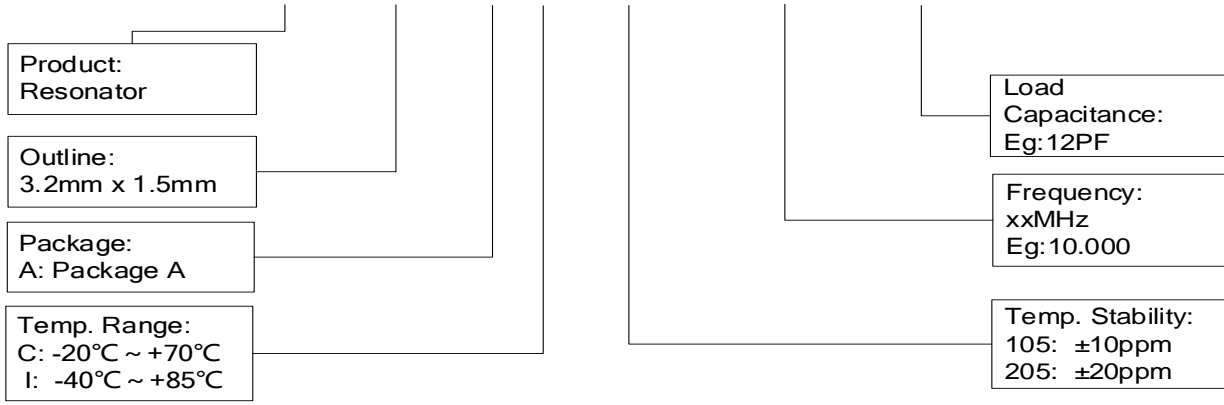


## Reliability Test Specifications

Test item	Specification	Conditions
Drop Test	GB/T2423.8	150CM height,fall freely onto concrete floor 3 times.
Mechanical Shock	GB/T2423.5	Device are shocked to half sine wave (1000G) three mutually perpendicular axes each 3 times. 0.5m sec.duration time.
Vibration Test	GB/T2423.10	Amplitude 1.52mm Time 20 min Enable Crystal from 10~2000Hz, X,Y,Z horizontal, 1time/ 2hours
Solderability Test	IEC60068-2-58	Solderability: 245±5°C Height: 0.5mm Time: 3±0.5second Scaling powder: rosin resin methanol solvent (1:4)
High Temp Storage	GB/T2423.2	500±12 hours at +125°C±2°C
Low TEMP Storage	GB/T2423.1	500±12 hours at -40°C±2°C
Temp Cycle Test	GB/T2423.22	10 cycles as below table 
Temp & Hum Cycle Test	GB/T2423.3	Temperature:85°C±3°C Humidity:85% 500h

## Ordering Guide

BC 3215 A X XXX - XX - X



**Eg:** BC3215AI205-32.768-12.5PF